Basic FIB Circuit Edit – Back Side Sample Application Training
Abbreviated* Syllabus.

1. Economics of Circuit Edit
2. Backside Circuit Edit flow chart
3. Sample preparation, cleaning, loading and alignment
4. Through-silicon navigation: Optical, FIB, CAD, beam placement.
5. Choice of gas chemistries
6. Choice of apertures, beam currents, imaging modes
7. Local Si thinning and endpoint detection
8. Circuitry access, via milling, dose estimation
9. Via endpoint concept and detection methods
10. Via filling, conductor deposition, connections
11. Line cut, and isolation in the via
12. Specifics of Cu technology
13. Interlayer isolation, dielectric deposition
14. Probe points

*Detailed syllabus is available upon request sent to: info@partbeamsystech.com